

- **Ultrafast Operation . . . 7.6 ns (Typ)**
- **Low Positive Supply Current**
10.6 mA (Typ)
- **Operates From a Single 5-V Supply or From a Split ± 5 -V Supply**
- **Complementary Outputs**
- **Low Offset Voltage**
- **No Minimum Slew Rate Requirement**
- **Output Latch Capability**
- **Functional Replacement to the LT1016**

description

The TL3016 is an ultrafast comparator designed to interface directly to TTL logic while operating from either a single 5-V power supply or dual ± 5 -V supplies. It features extremely tight offset voltage and high gain for precision applications. It has complementary outputs that can be latched using the LATCH ENABLE terminal. Figure 1 shows the positive supply current of this comparator. The TL3016 only requires 10.6 mA (typical) to achieve a propagation delay of 7.6 ns.

The TL3016 is a pin-for-pin functional replacement for the LT1016 comparator, offering higher speed operation but consuming half the power.

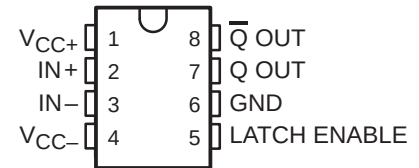
AVAILABLE OPTIONS

T_A	PACKAGED DEVICES		CHIP FORM [‡] (Y)
	SMALL OUTLINE [†] (D)	TSSOP (PW)	
0°C to 70°C	TL3016CD	TL3016CPWLE	TL3016Y
–40°C to 85°C	TL3016ID	TL3016IPWLE	—

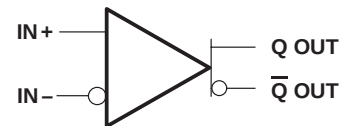
[†] The PW packages are available left-ended taped and reeled only.

[‡] Chip forms are tested at $T_A = 25^\circ\text{C}$ only.

D AND PW PACKAGE (TOP VIEW)



symbol (each comparator)



POSITIVE SUPPLY CURRENT vs FREE-AIR TEMPERATURE

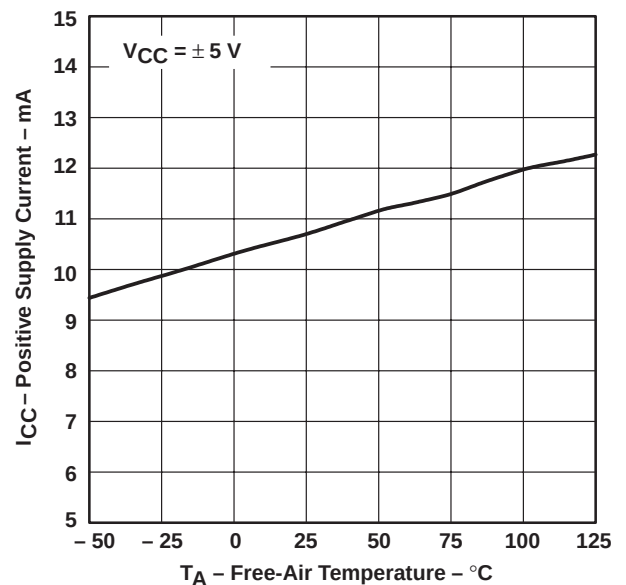


Figure 1



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

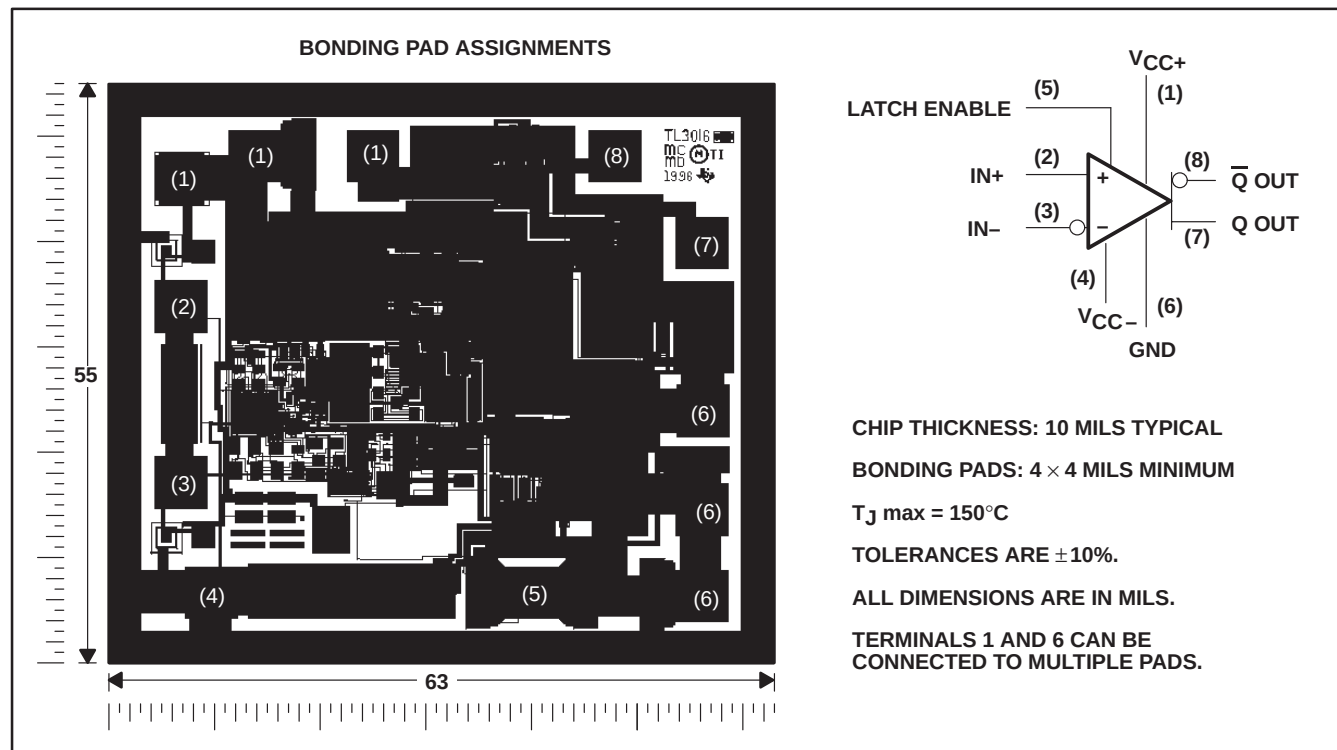
**TEXAS
INSTRUMENTS**

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TL3016Y chip information

This chip displays characteristics similar to the TL3016C. Thermal compression or ultrasonic bonding may be used on the doped-aluminum bonding pads. Chips may be mounted with conductive epoxy or a gold-silicon preform.



COMPONENT COUNT	
Bipolars	53
MOSFETs	49
Resistors	46
Capacitors	14

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V_{DD} (see Note 1)	– 7 V to 7 V
Differential input voltage, V_{ID} (see Note 2)	7 V
Input voltage range, V_I	7 V
Input voltage, V_I (LATCH ENABLE)	7 V
Output current, I_O	± 20 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A	–40°C to 85°C
Storage temperature range, T_{stg}	– 65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to network ground.
2. Differential voltages are at $IN+$ with respect to $IN-$.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING
D	725 mW	5.8 mW/°C	464 mW
PW	525 mW	4.2 mW/°C	336 mW

TL3016, TL3016Y

ULTRA-FAST LOW-POWER

PRECISION COMPARATORS

SLCS130D – MARCH 1997 – REVISED MARCH 2000

electrical characteristics at specified operating free-air temperature, $V_{DD} = \pm 5\text{ V}$, $V_{LE} = 0$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	TL3016C			TL3016I			UNIT
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IO}	Input offset voltage	$T_A = 25^\circ\text{C}$		0.5	3		0.5	3	mV
		$T_A = \text{full range}$			3.5			3.5	
α_{VIO}	Temperature coefficient of input offset voltage			–4.8			–4.5		$\mu\text{V}/^\circ\text{C}$
I_{IO}	Input offset current	$T_A = 25^\circ\text{C}$		0.1	0.6		0.1	0.6	μA
		$T_A = \text{full range}$			0.9			1.3	
I_{IB}	Input bias current	$T_A = 25^\circ\text{C}$		6	10		6	10	μA
		$T_A = \text{full range}$			10			10	
V_{ICR}	Common-mode input voltage range	$V_{DD} = \pm 5\text{ V}$	–3.75		3.5	–3.75		3.5	V
		$V_{DD} = 5\text{ V}$	1.25		3.5	1.25		3.5	
CMRR	Common-mode rejection ratio	$-3.75 \leq V_{IC} \leq 3.5\text{ V}$, $T_A = 25^\circ\text{C}$	80	97		80	97		dB
k_{SVR}	Supply-voltage rejection ratio	Positive supply: $4.6\text{ V} \leq +V_{DD} \leq 5.4\text{ V}$, $T_A = 25^\circ\text{C}$	60	72		60	72		dB
		Negative supply: $-7\text{ V} \leq -V_{DD} \leq -2\text{ V}$, $T_A = 25^\circ\text{C}$	80	100		80	100		
V_{OL}	Low-level output voltage	$I(\text{sink}) = 4\text{ mA}$, $V+ \leq 4.6\text{ V}$, $T_A = 25^\circ\text{C}$		500	600		500	600	mV
		$I(\text{sink}) = 10\text{ mA}$, $V+ \leq 4.6\text{ V}$, $T_A = 25^\circ\text{C}$		750			750		
V_{OH}	High-level output voltage	$V+ \leq 4.6\text{ V}$, $T_A = 25^\circ\text{C}$, $I_O = 1\text{ mA}$	3.6	3.9		3.6	3.9		V
		$V+ \leq 4.6\text{ V}$, $T_A = 25^\circ\text{C}$, $I_O = 10\text{ mA}$	3.4	3.7		3.4	3.7		
I_{DD}	Positive supply current	$T_A = \text{full range}$		10.6	12.5		10.6	12.5	mA
	Negative supply current		–1.8	–1.3		–2.4	–1.3		
V_{IL}	Low-level input voltage (LATCH ENABLE)				0.8			0.8	V
V_{IH}	High-level input voltage (LATCH ENABLE)			2			2		V
I_{IL}	Low-level input current (LATCH ENABLE)	$V_{LE} = 0$		0	1		0	1	μA
		$V_{LE} = 2\text{ V}$		24	39		24	45	

† Full range for the TL3016C is $T_A = 0^\circ\text{C}$ to 70°C . Full range for the TL3016I is $T_A = -40^\circ\text{C}$ to 85°C .

‡ All typical values are measures with $T_A = 25^\circ\text{C}$.



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switching characteristics, $V_{DD} = \pm 5\text{ V}$, $V_{LE} = 0$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		TL3016C			TL3016I			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
t_{pd1}	Propagation delay time‡	$\Delta V_I = 100\text{ mV}$, $V_{OD} = 5\text{ mV}$	$T_A = 25^\circ\text{C}$		7.8	10		7.8	10	ns
			$T_A = \text{full range}$		7.8	11.2		7.8	12.2	
		$\Delta V_I = 100\text{ mV}$, $V_{OD} = 20\text{ mV}$	$T_A = 25^\circ\text{C}$		7.6	10		7.6	10	
			$T_A = \text{full range}$		7.6	11.2		7.6	12.2	
$t_{sk(p)}$	Pulse skew ($ t_{pd+} - t_{pd-} $)	$\Delta V_I = 100\text{ mV}$, $V_{OD} = 5\text{ mV}$, $T_A = 25^\circ\text{C}$			0.5			0.5		ns
t_{su}	Setup time, LATCH ENABLE				2.5			2.5		ns

† Full range for the TL3016C is 0°C to 70°C . Full range for the TL3016I is -40°C to 85°C .

‡ t_{pd1} cannot be measured in automatic handling equipment with low values of overdrive. The TL3016 is 100% tested with a 1-V step and 500-mV overdrive at $T_A = 25^\circ\text{C}$ only. Correlation tests have shown that t_{pd1} limits given can be ensured with this test, if additional dc tests are performed to ensure that all internal bias conditions are correct. For low overdrive conditions, V_{OS} is added to the overdrive.

TYPICAL CHARACTERISTICS

Table of Graphs

			FIGURE
I_{CC}	Positive supply current	vs Input voltage	2
		vs Frequency	3
		vs Free-air temperature	4
I_{CC}	Negative supply current	vs Free-air temperature	5
t_{pd}	Propagation delay time	vs Overdrive voltage	6
		vs Supply voltage	7
		vs Input impedance	8
		vs Load capacitance	9
		vs Free-air temperature	10
V_{IC}	Common-mode input voltage	vs Free-air temperature	11
	Input threshold voltage (LATCH ENABLE)	vs Free-air temperature	12
V_O	Output voltage	vs Output source current	13
		vs Output sink current	14
I_I	Input current (LATCH ENABLE)	vs Input voltage	15

TYPICAL CHARACTERISTICS

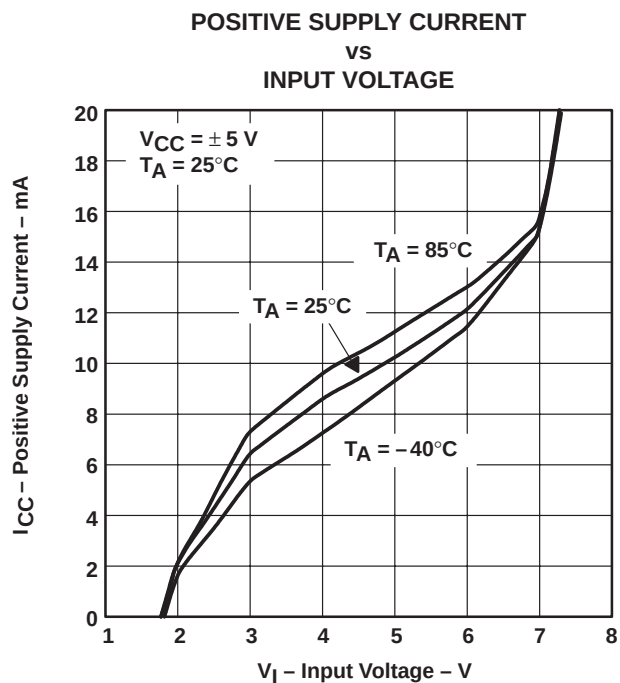


Figure 2

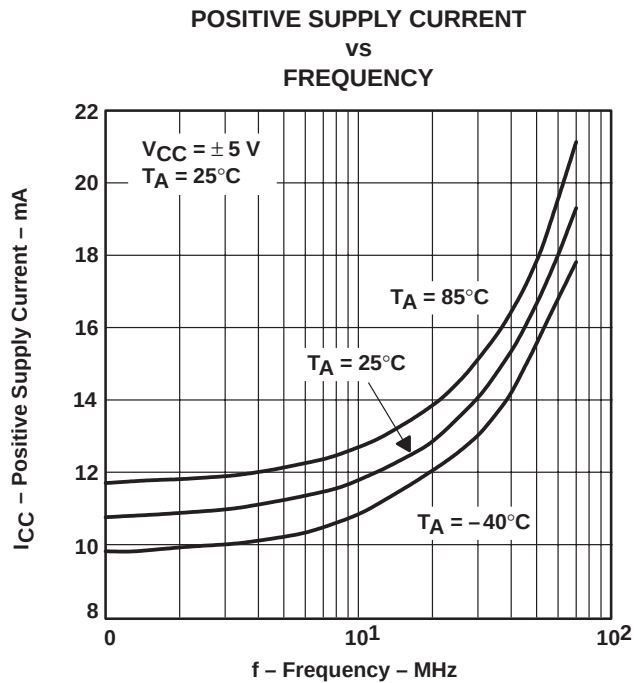


Figure 3

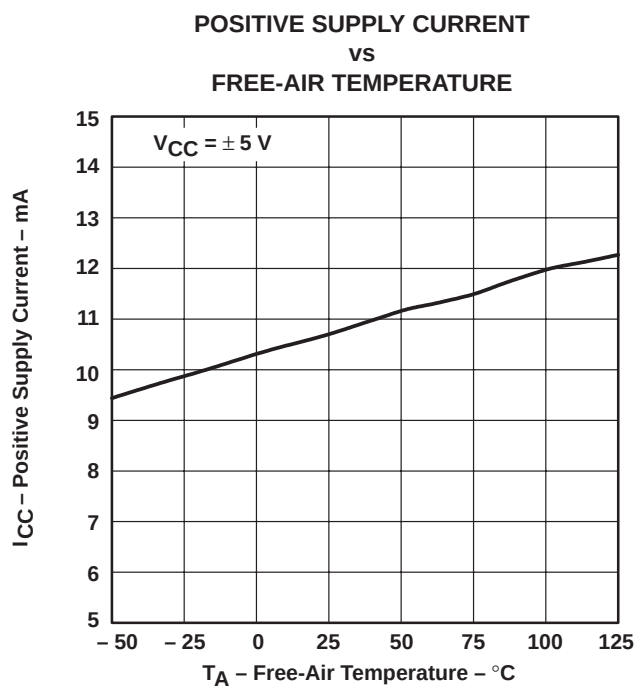


Figure 4

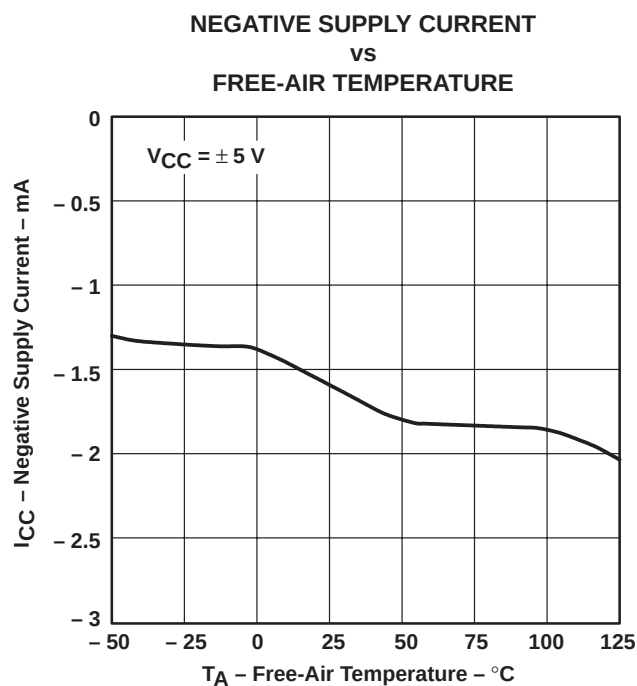


Figure 5

TYPICAL CHARACTERISTICS

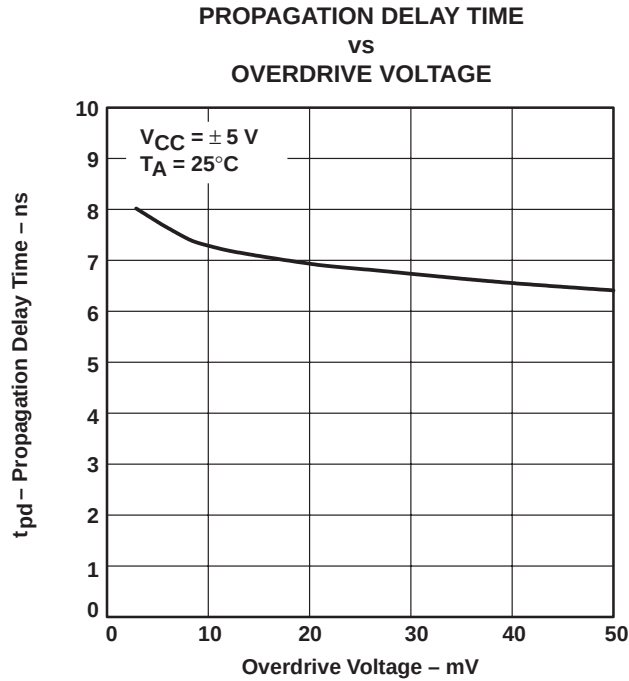


Figure 6

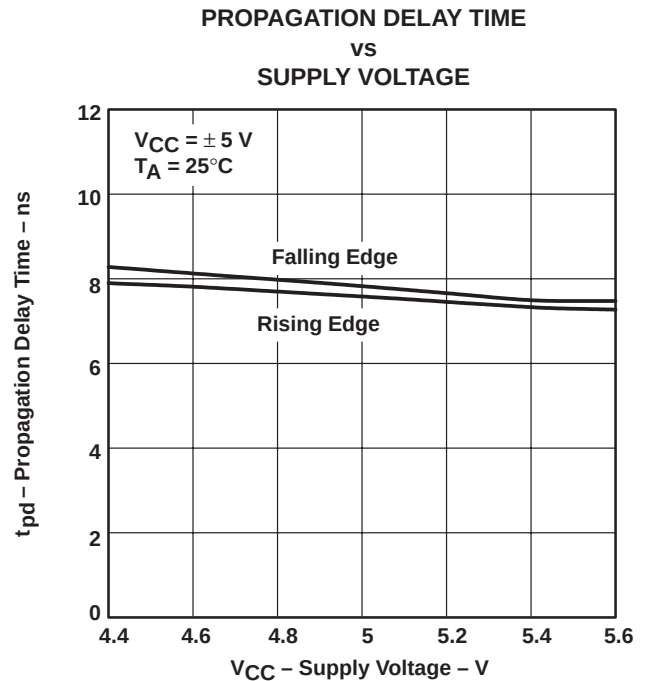


Figure 7

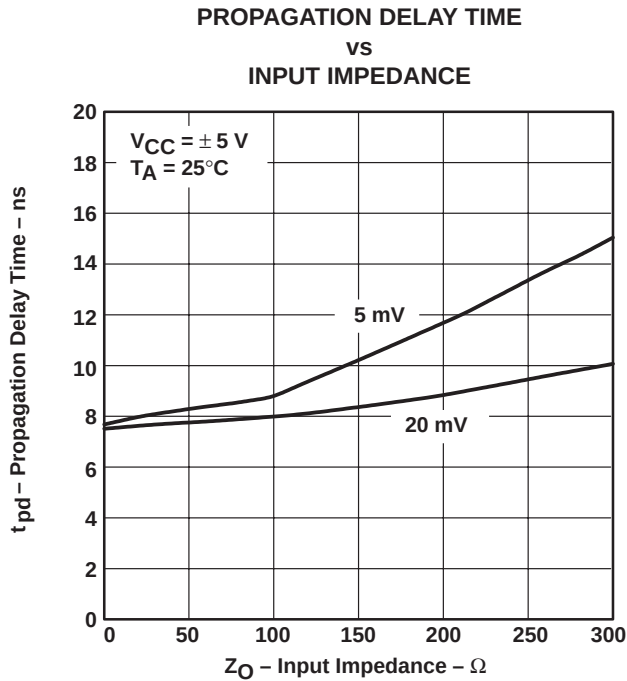


Figure 8

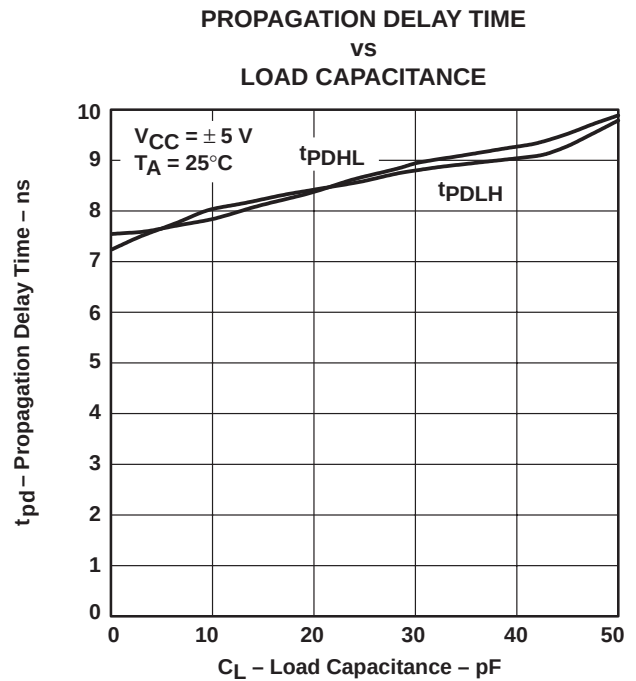


Figure 9

TYPICAL CHARACTERISTICS

PROPAGATION DELAY TIME
 VS
 FREE-AIR TEMPERATURE

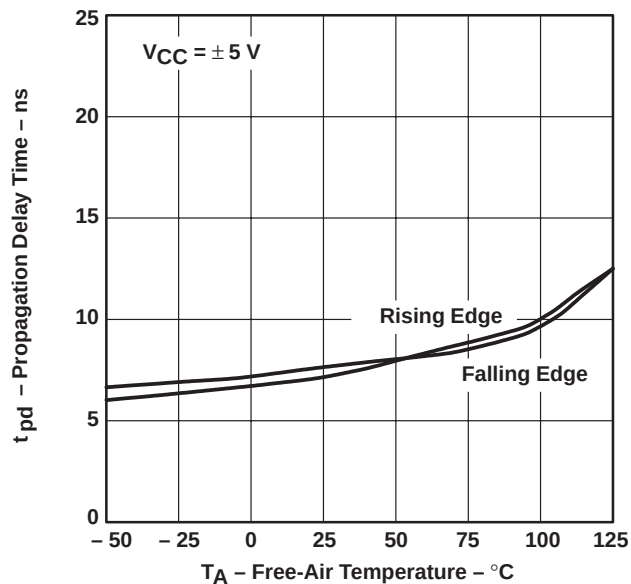


Figure 10

COMMON-MODE INPUT VOLTAGE
 VS
 FREE-AIR TEMPERATURE

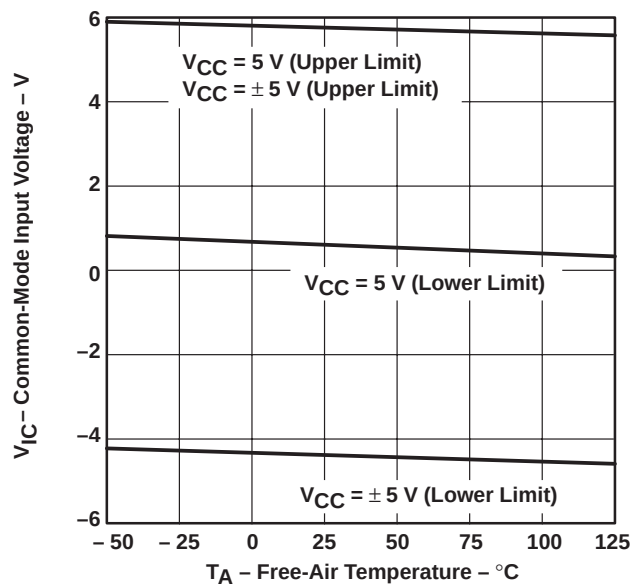


Figure 11

INPUT THRESHOLD VOLTAGE (LATCH ENABLE)
 VS
 FREE-AIR TEMPERATURE

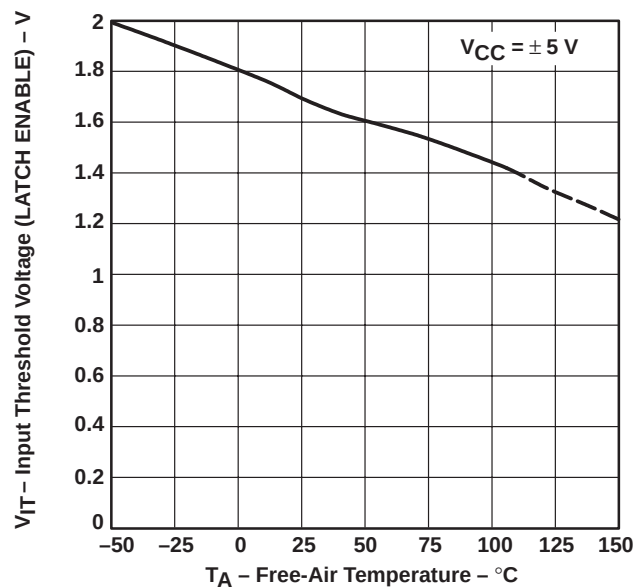


Figure 12

OUTPUT VOLTAGE
 VS
 OUTPUT SOURCE CURRENT

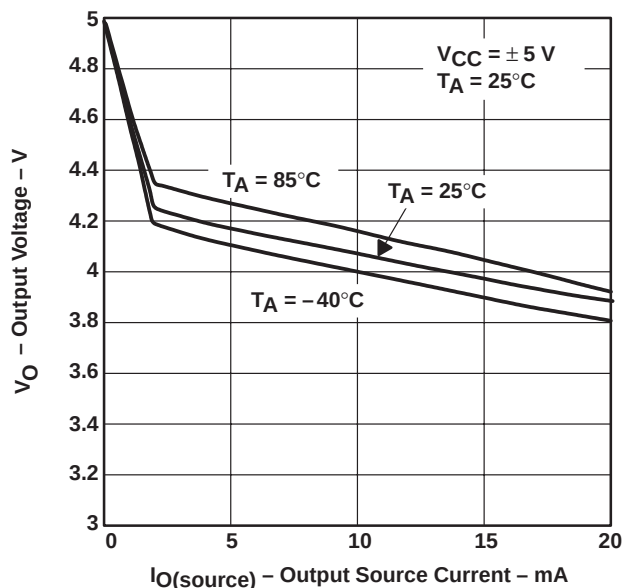


Figure 13

TYPICAL CHARACTERISTICS

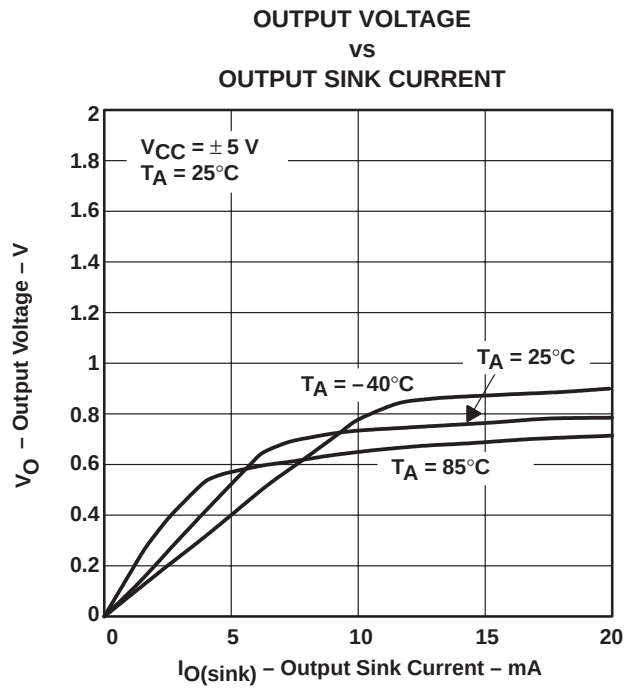


Figure 14

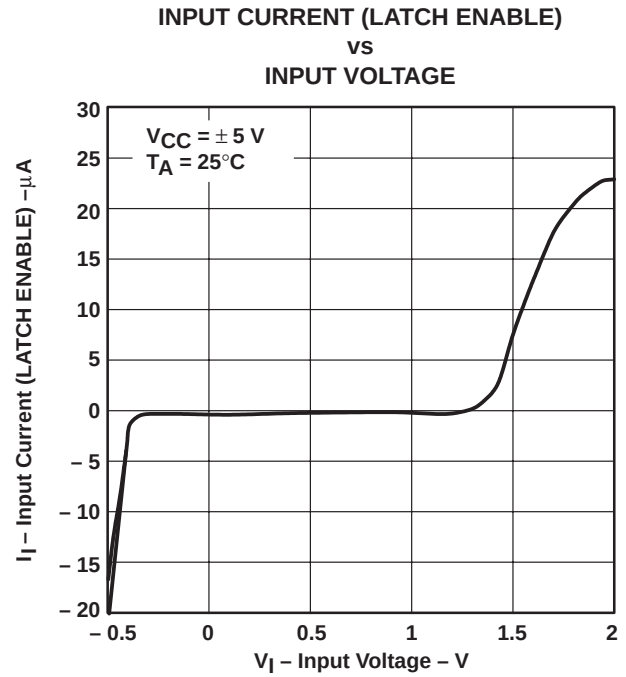


Figure 15

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TL3016CD	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	3016C
TL3016CD.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	3016C
TL3016CDG4	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	3016C
TL3016CDR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	3016C
TL3016CDR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	3016C
TL3016CPW	Active	Production	TSSOP (PW) 8	150 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	T3016
TL3016CPW.A	Active	Production	TSSOP (PW) 8	150 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	T3016
TL3016CPWR	Active	Production	TSSOP (PW) 8	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	T3016
TL3016CPWR.A	Active	Production	TSSOP (PW) 8	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	T3016
TL3016ID	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	3016I
TL3016ID.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	3016I
TL3016IDR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	3016I
TL3016IDR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	3016I
TL3016IDRG4	Active	Production	SOIC (D) 8	2500 LARGE T&R	-	Call TI	Call TI	-40 to 85	
TL3016IPW	Active	Production	TSSOP (PW) 8	150 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3016
TL3016IPW.A	Active	Production	TSSOP (PW) 8	150 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3016
TL3016IPWR	Active	Production	TSSOP (PW) 8	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3016
TL3016IPWR.A	Active	Production	TSSOP (PW) 8	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3016

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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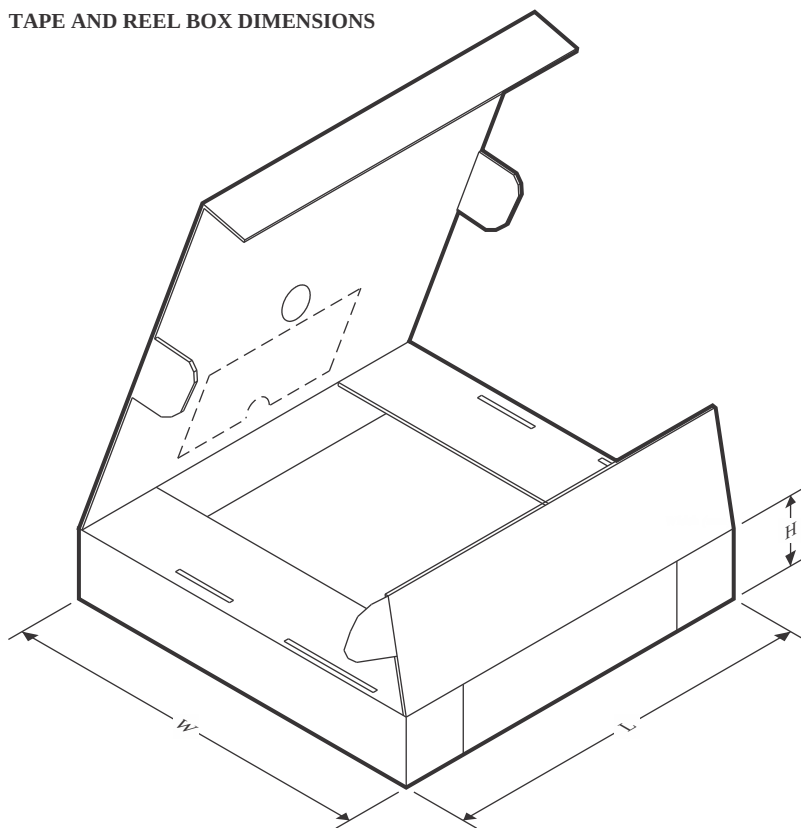
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL3016CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL3016CPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TL3016IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL3016IPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

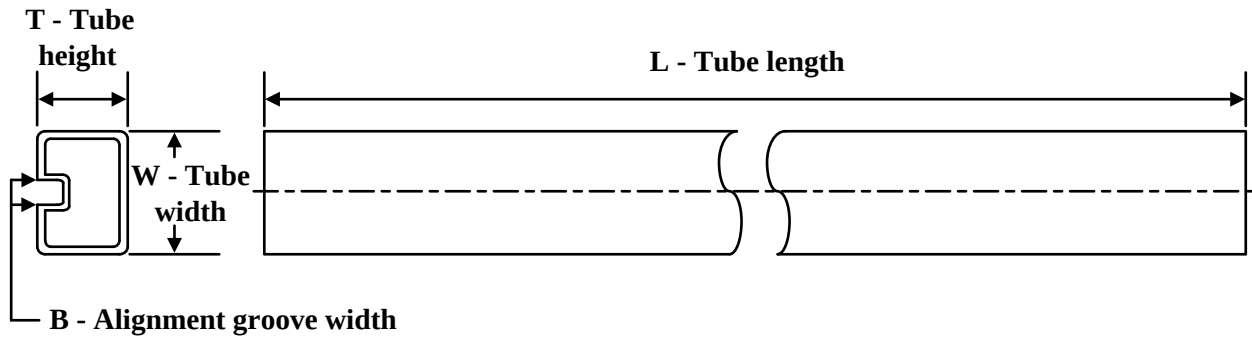
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

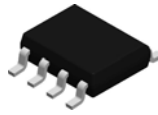
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL3016CDR	SOIC	D	8	2500	350.0	350.0	43.0
TL3016CPWR	TSSOP	PW	8	2000	353.0	353.0	32.0
TL3016IDR	SOIC	D	8	2500	350.0	350.0	43.0
TL3016IPWR	TSSOP	PW	8	2000	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
TL3016CD	D	SOIC	8	75	505.46	6.76	3810	4
TL3016CD.A	D	SOIC	8	75	505.46	6.76	3810	4
TL3016CDG4	D	SOIC	8	75	505.46	6.76	3810	4
TL3016CPW	PW	TSSOP	8	150	530	10.2	3600	3.5
TL3016CPW.A	PW	TSSOP	8	150	530	10.2	3600	3.5
TL3016ID	D	SOIC	8	75	505.46	6.76	3810	4
TL3016ID.A	D	SOIC	8	75	505.46	6.76	3810	4
TL3016IPW	PW	TSSOP	8	150	530	10.2	3600	3.5
TL3016IPW.A	PW	TSSOP	8	150	530	10.2	3600	3.5

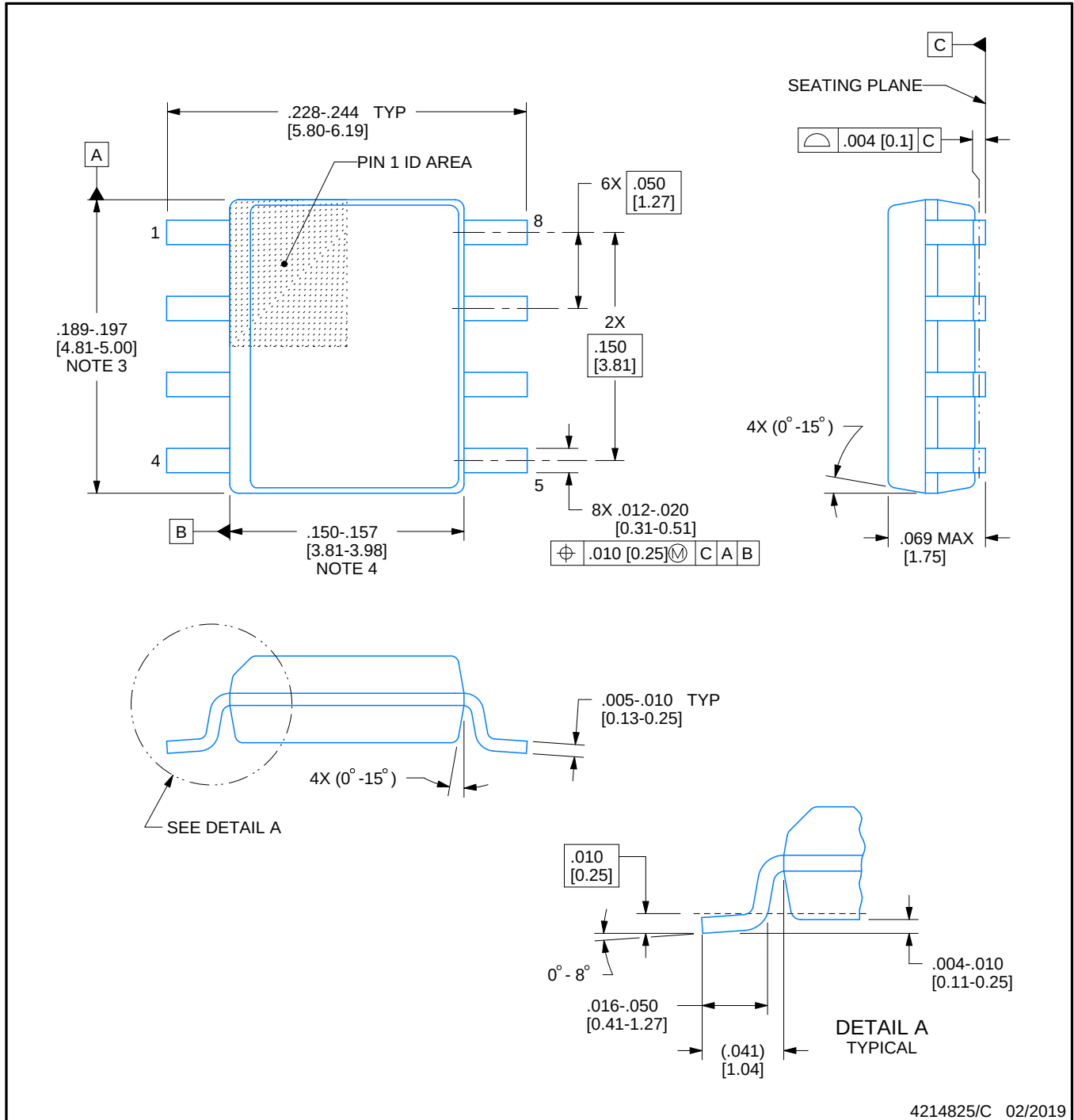


D0008A

PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

NOTES:

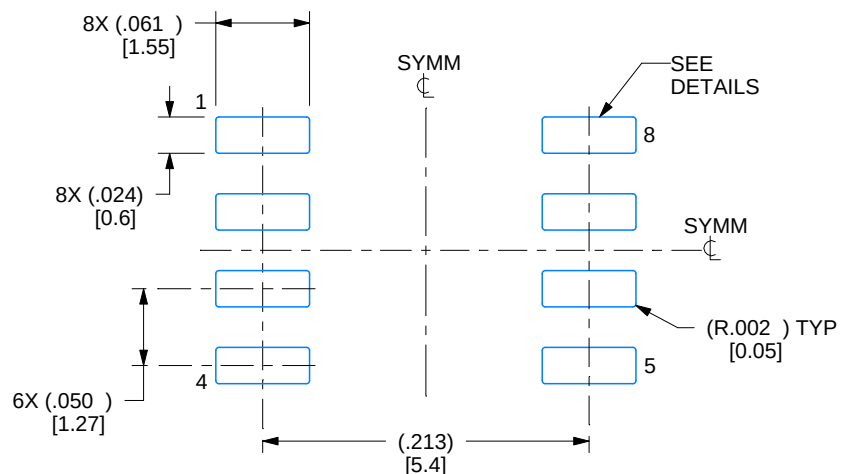
1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

EXAMPLE BOARD LAYOUT

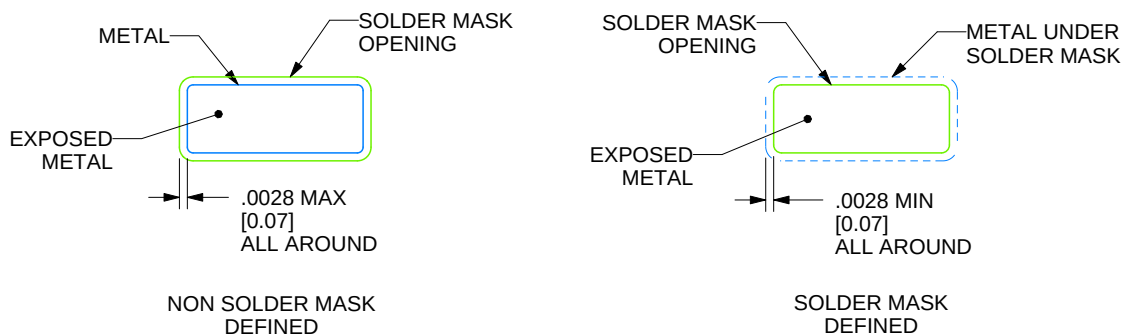
D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

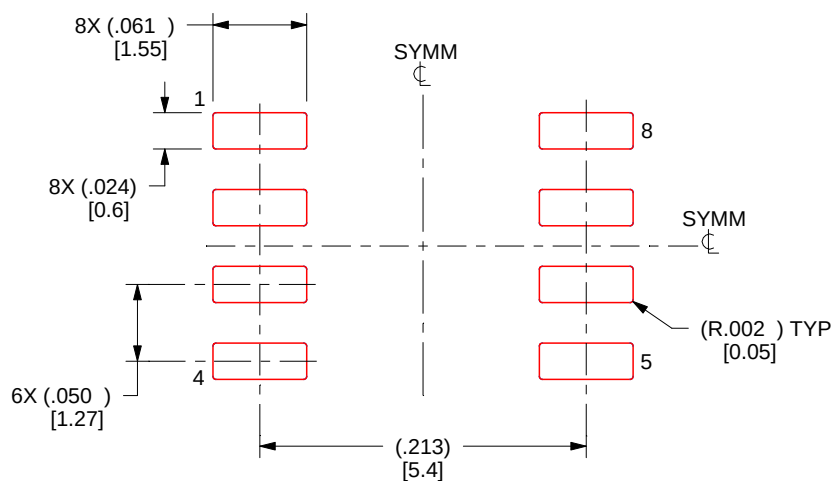
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

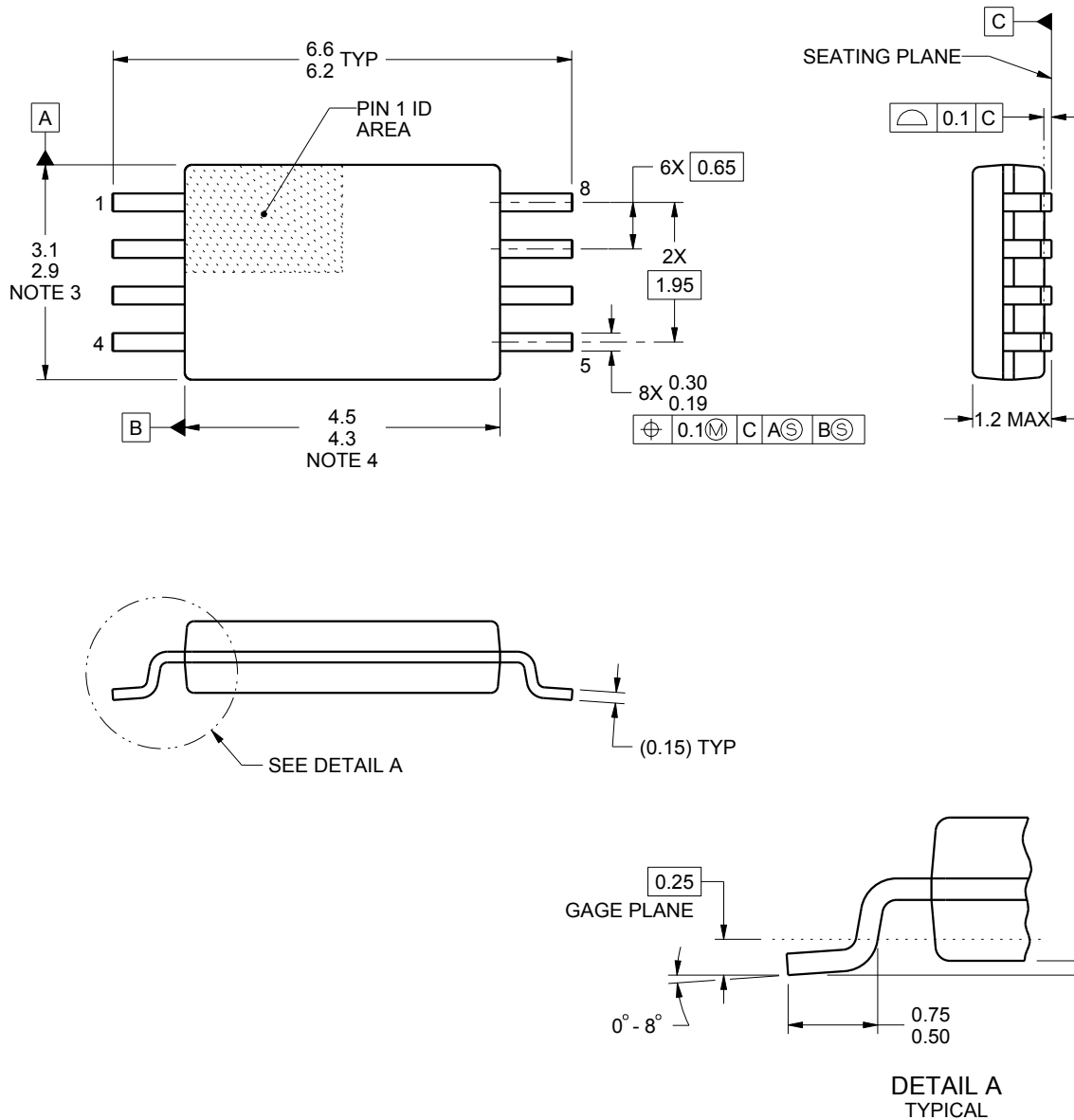
PW0008A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4221848/A 02/2015

NOTES:

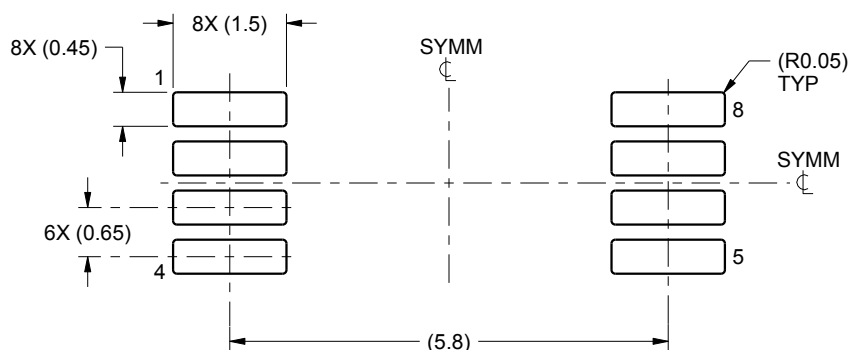
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153, variation AA.

EXAMPLE BOARD LAYOUT

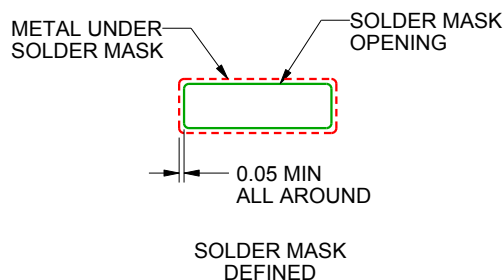
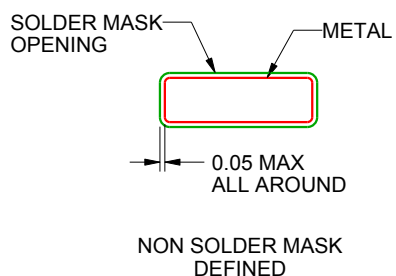
PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

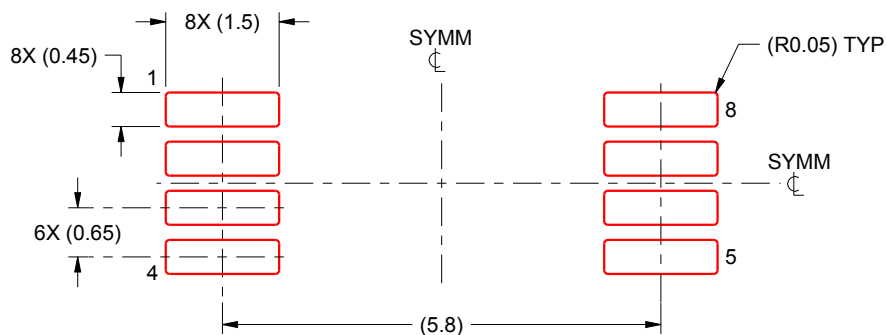
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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